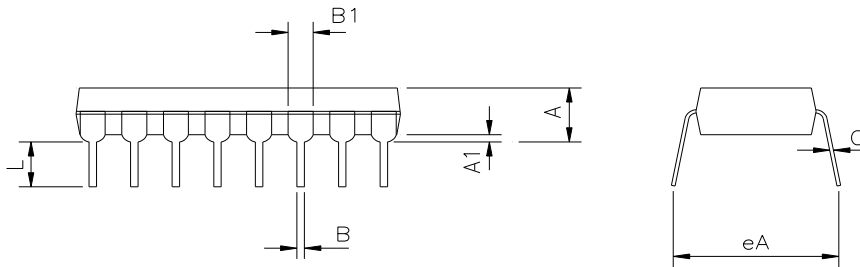
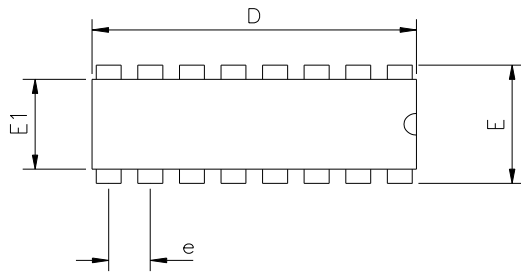


300 MIL PDIP  
PLASTIC DUAL IN-LINE PACKAGE

PACKAGE INFORMATION



NOTES

1. SPADE WIDTH, LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. TOLERANCE AS PER LEAD FRAME SUPPLIER
4. PACKAGE FINISH—MATTE FINISH ON ALL SIDES(8±2 MICRONS Rz)
5. ALLOWABLE MOLD FLASH IS 10 MILS PER SIDE.
6. DIMENSIONS ARE GIVEN IN INCHES.

JEDEC #	MS-001BA		MS-001AA		MS-001AB		MS-001AC		MS-001AD	
TYPE	8 LEAD		14 LEAD		16 LEAD		18 LEAD		20 LEAD	
SYMBOL	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
A	0.130	0.170	0.130	0.170	0.130	0.170	0.130	0.170	0.130	0.170
A1	0.015	0.040	0.015	0.040	0.015	0.040	0.015	0.040	0.015	0.040
B	0.016	0.020	0.016	0.020	0.016	0.020	0.016	0.020	0.016	0.020
B1	0.045	0.070	0.045	0.070	0.045	0.070	0.045	0.070	0.045	0.070
C	0.009	0.012	0.009	0.012	0.009	0.012	0.009	0.012	0.009	0.012
D	0.345	0.365	0.745	0.765	0.745	0.765	0.890	0.910	1.020	1.040
E	0.300	0.325	0.300	0.325	0.300	0.325	0.300	0.325	0.300	0.325
E1	0.240	0.270	0.240	0.270	0.240	0.270	0.240	0.270	0.240	0.270
e	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110
eA	0.310	0.380	0.310	0.380	0.310	0.380	0.310	0.380	0.310	0.380
L	0.120	0.140	0.120	0.140	0.120	0.140	0.120	0.140	0.120	0.140

PREPARED BY	NK	REF. NO.	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	NJC	DIM-PDIP-01	0	
APPROVED BY	RM		DATE	

